

2023 / 2024 MPW schedule

Last updated: November 29, 2023

MPW name	Fab	Processes	Tape-In	Ship Date
SB*18- B5311	NPB - Fab 3	SiGe BiCMOS 0.18um	7-11-23	1-18-24
SB*18 - B5314	NPB - Fab 3	SiGe BiCMOS 0.18um	9-05-23	3-14-24
SB*/CA/13* - B5316	NPB - Fab 3	SiGe BiCMOS / RF CMOS 0.13um	10-03-23	5-31-24
CS18* - B5313	MH - Fab 2	CMOS-SOI 0.18um	10-10-23	
CA18 - B5317	NPB - Fab 3	RFCMOS 0.18um	10-17-23	3-29-24
PH18M* - B5318	NPB - Fab 3	SiPho 0.18um	10-31-23	3-15-24
SB*18 - B5319	NPB - Fab 3	SiGe BiCMOS 0.18um	11-14-23	5-24-24
SB*18 – B5660	NPB - Fab 3	SiGe BiCMOS 0.18um	11-14-23	5-24-24
SH423T18NOV	MH - Fab 2	CIS 0.18um Image Sensor CMOS+ 0.16um, 0.18um RF, RFID, PM	11-14-23 11-21-23	
27th MPW - Tonami, Japan	TPSCo - Fab 5	TS18 : CMOS 0.18u & 0.16u, PM, PM_SOI	11-27-23	
CA18 - B5600	NPB - Fab 3	RFCMOS 0.18um	1-09-24	6-21-24
28th MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB	1-22-24	
SB*18 - B5601	NPB - Fab 3	SiGe BiCMOS 0.18um	1-23-24	8-01-24
PH18MA - B5602	NPB - Fab 3	SiPho 0.18um	2-06-24	6-21-24
SH124T18FEB	MH - Fab 2	0.18 BSI Stacking on 0.13	2-14-24	
29th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	2-19-24	
PH18DA - B5603	NPB - Fab 3	SiPho 0.18um	2-20-24	10-25-24
SB*18 - B5604	NPB - Fab 3	SiGe BiCMOS 0.18um	3-05-24	9-10-24
SH224T18MAR	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	3-10-24 3-15-24	
28th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	3-18-24	
CA18 - B5606	NPB - Fab 3	RFCMOS 0.18um	4-02-24	9-13-24
30th MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	4-08-24	
CS18* - B5608	MH - Fab 2	CMOS-SOI 0.18um	4-30-24	
PH18M* - B5609	NPB - Fab 3	SiPho 0.18um	5-14-24	9-27-24
SH324T18MAY	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	5-14-24 5-21-24	
29th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	5-27-24	
SB*/CA13* - B5610	NPB - Fab 3	SiGe BiCMOS/RF CMOS 0.13um	5-28-24	1-24-25
SB*18 - B5611	NPB - Fab 3	SiGe BiCMOS 0.18um	6-11-24	12-19-24

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31st MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB	7-08-24	
CA18 - B5613	NPB - Fab 3	RFCMOS 0.18um	7-16-24	12-27-24
PH18DA - B5614	NPB - Fab 3	SiPho 0.18um	7-30-24	4-4-25
SH424T18AUG	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	8-08-24 8-15-24	
SB*18 - B5615	NPB - Fab 3	SiGe BiCMOS 0.18um	8-13-24	2-20-25
30th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	8-26-24	
CS18* - B5616	MH - Fab 2	CMOS-SOI 0.18um	8-27-24	
PH18M* - B5617	NPB - Fab 3	SiPho 0.18um	9-10-24	1-24-25
32nd MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	9-24-24	
SB*18 - B5619	NPB - Fab 3	SiGe BiCMOS 0.18um	10-8-24	4-17-25
33rd MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	10-28-24	
CA18 - B5621	NPB - Fab 3	RFCMOS 0.18um	11-5-24	4-18-25
SH524T18NOV	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	11-14-24 11-21-24	
SB*18 - B5622	NPB - Fab 3	SiGe BiCMOS 0.18um	11-19-24	5-29-25
31st MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	11-25-24	

Notes: "Shuttles" (SH*) are run at Fab 2

* 0.13u MH – fab 2 Shuttle / MPW slots will be considered per needs

Please contact your customer account manager for additional information.

Fab2 - Tower Semiconductor 200mm wafer fabrication facility at Migdal Ha'emek, Israel

Fab3 - Tower Semiconductor 200mm wafer fabrication facility at Newport Beach, CA

Fab5 - Tower Semiconductor 200mm wafer fabrication facility at Tonami, Japan

Fab7 - Tower Semiconductor 300mm wafer fabrication facility at Uozu, Japan